

FIG. 1

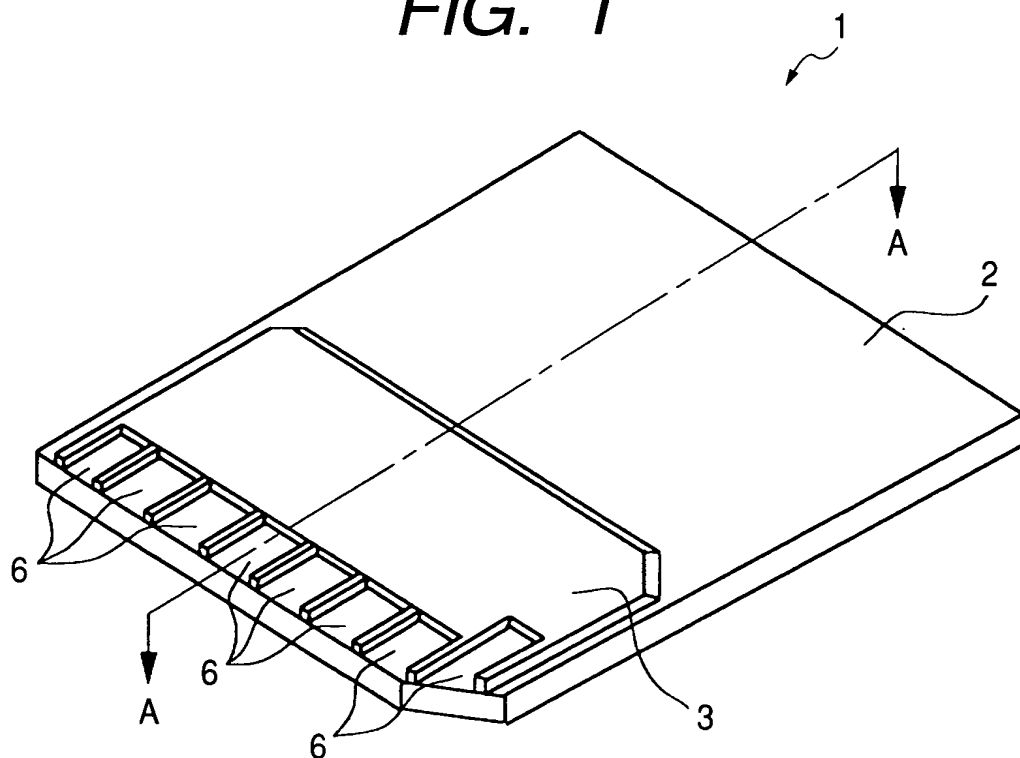
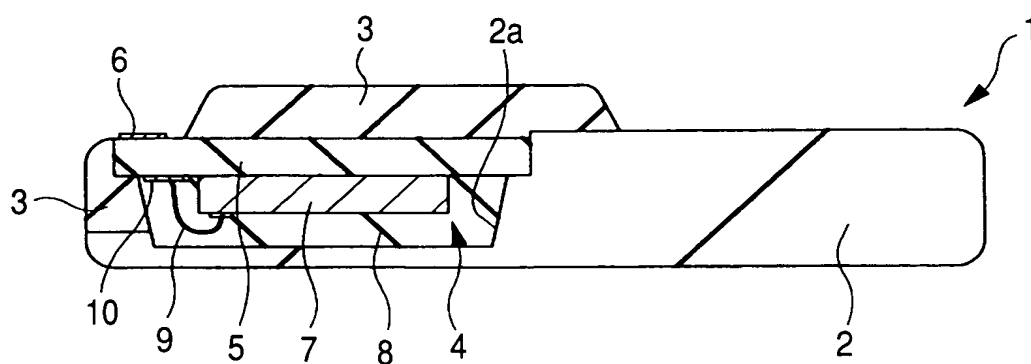


FIG. 2



- | | |
|---------------------|---------------------------------|
| 1: IC CARD | 6: EXTERNAL CONNECTION TERMINAL |
| 2: CASE | 7: SEMICONDUCTOR CHIP |
| 3: SEALING PORTION | 8: SEALING PORTION |
| 4: IC BODY | 9: BONDING WIRE |
| 5: WIRING SUBSTRATE | |

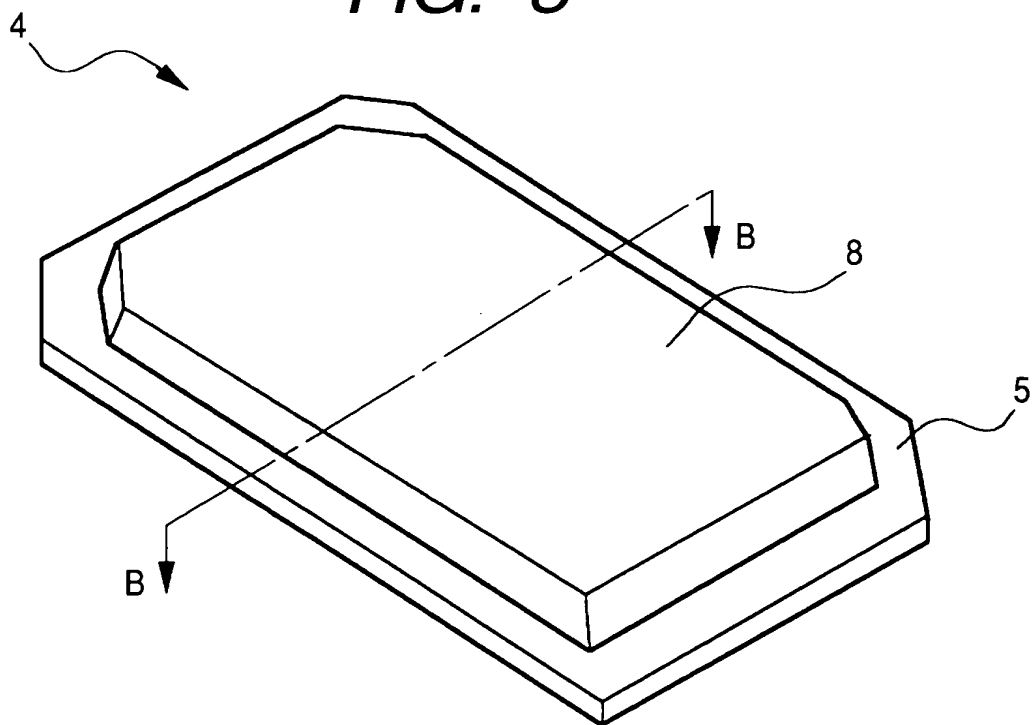
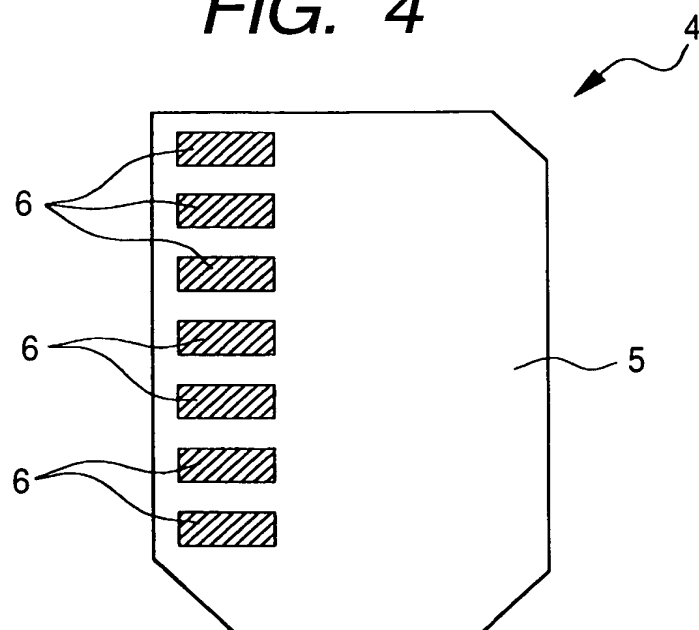
FIG. 3**FIG. 4**

FIG. 5

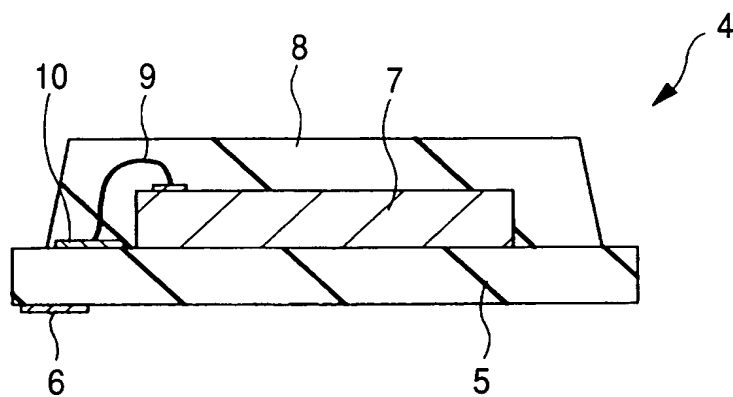


FIG. 6

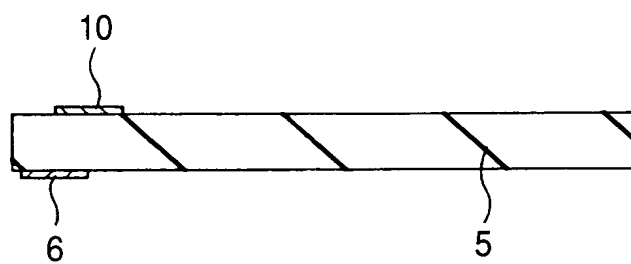


FIG. 7

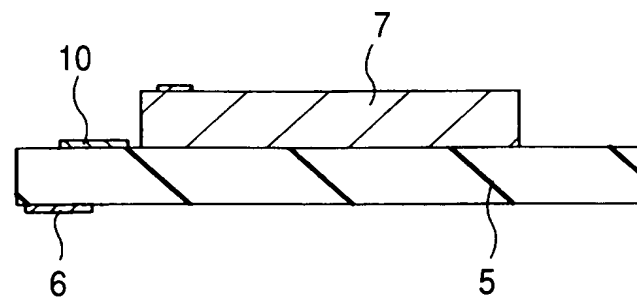


FIG. 8

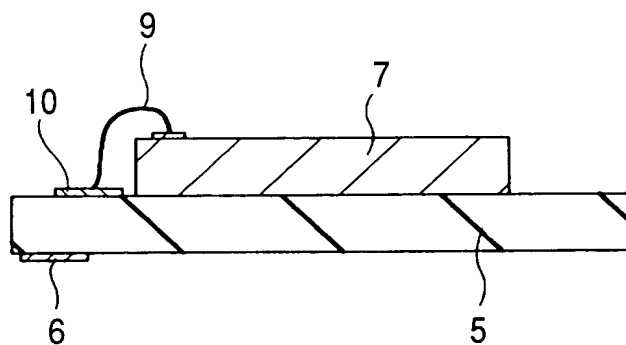


FIG. 9

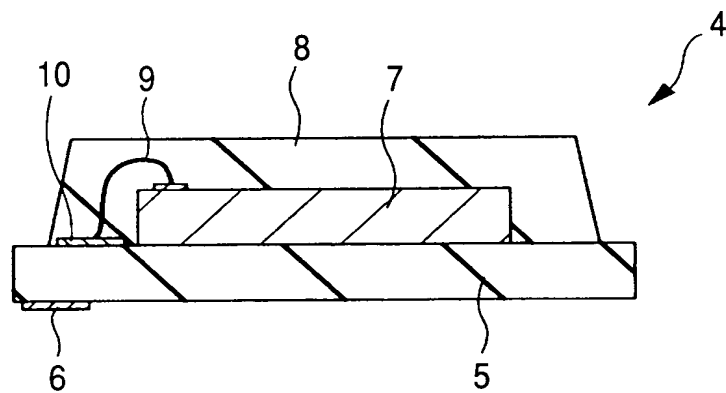


FIG. 10

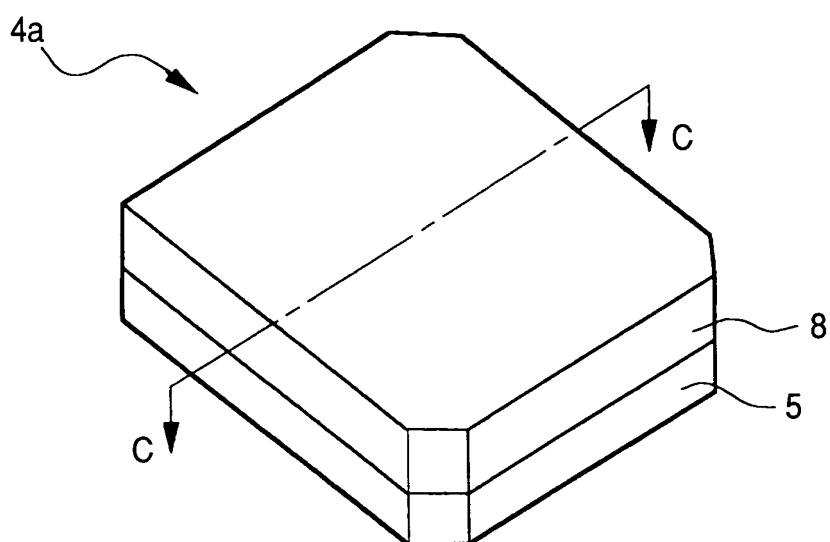


FIG. 11

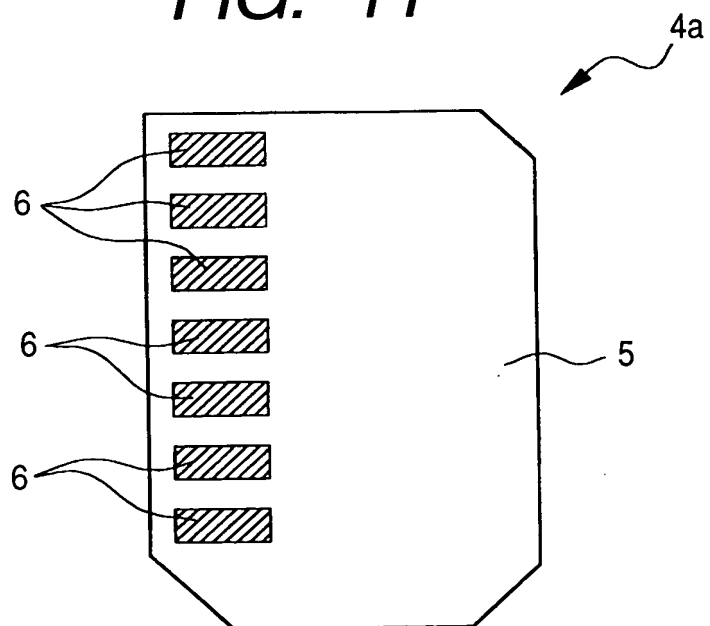


FIG. 12

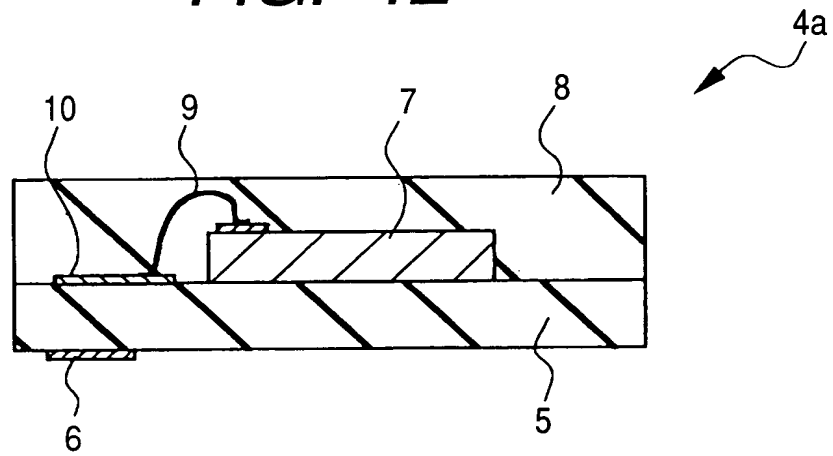


FIG. 13

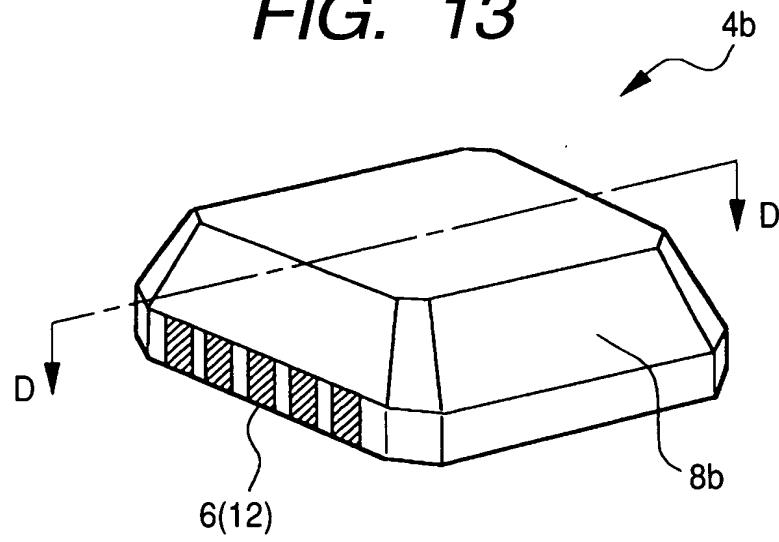


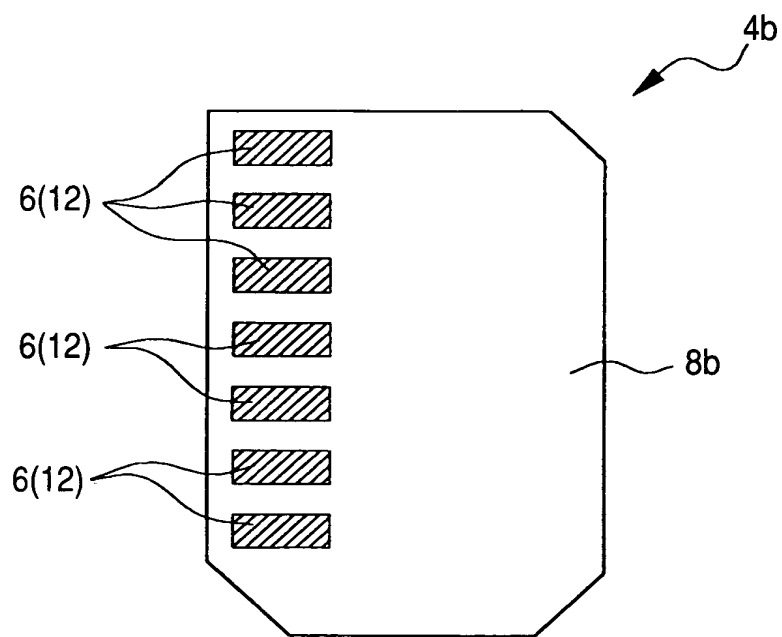
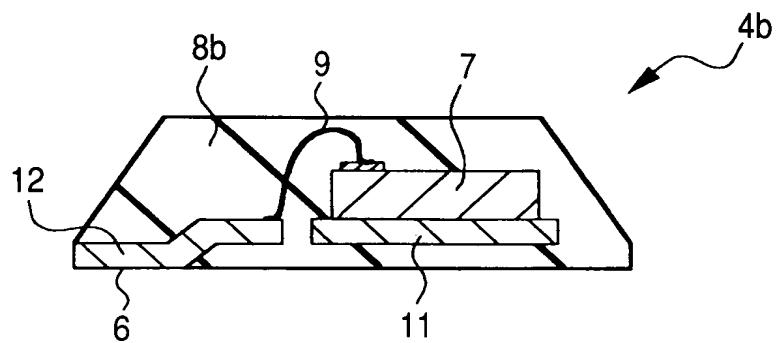
FIG. 14**FIG. 15**

FIG. 16

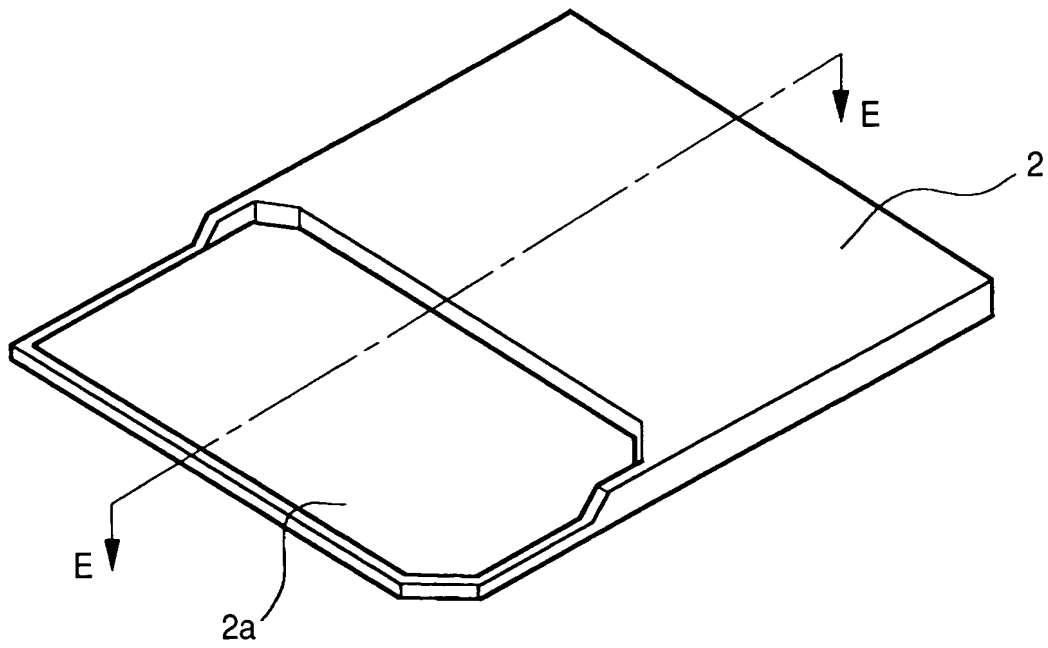


FIG. 17

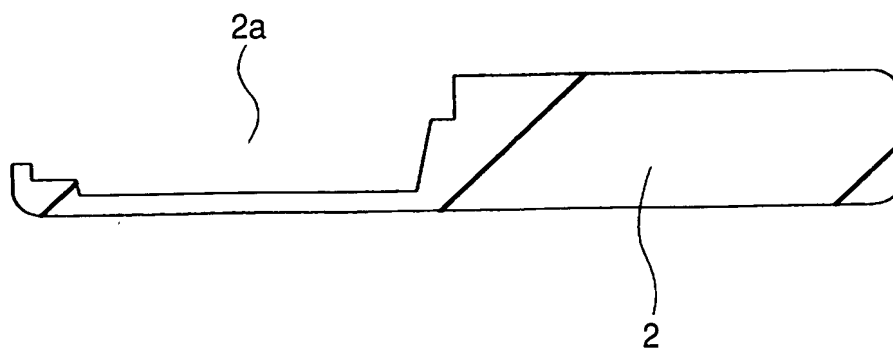


FIG. 18

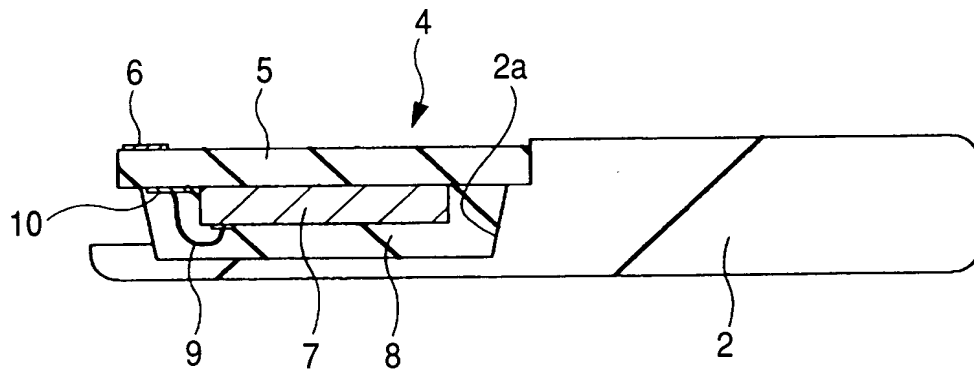


FIG. 19

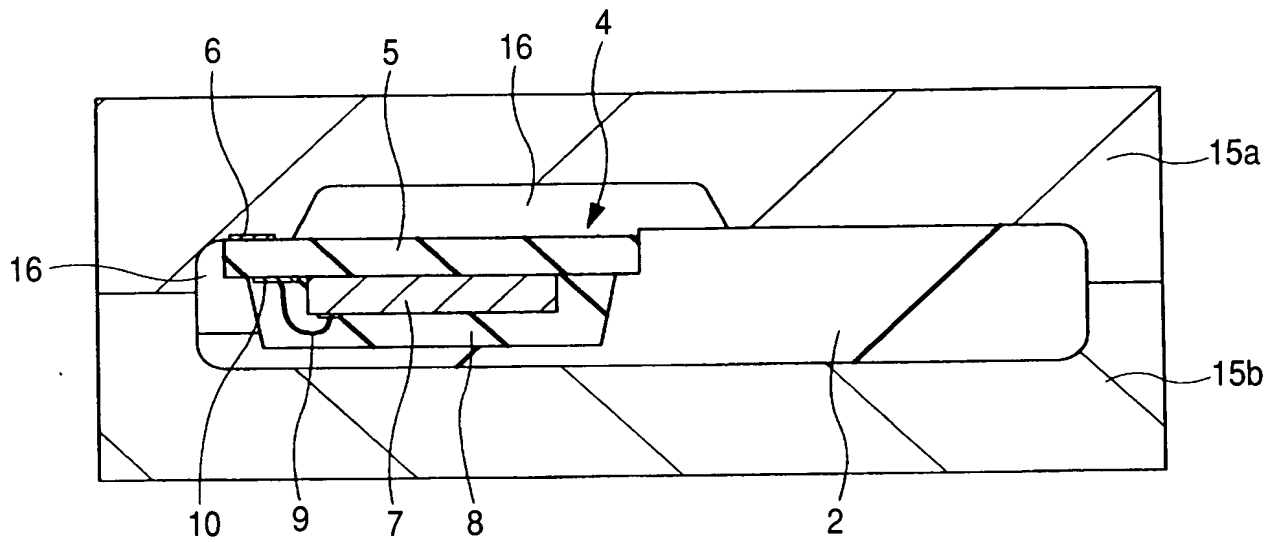


FIG. 20

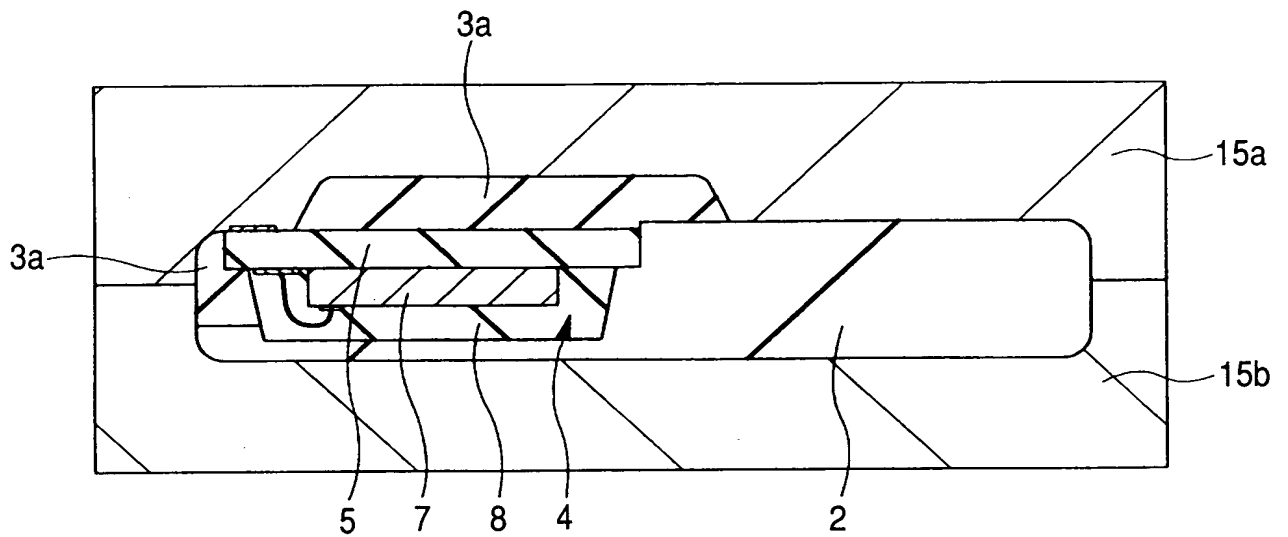


FIG. 21

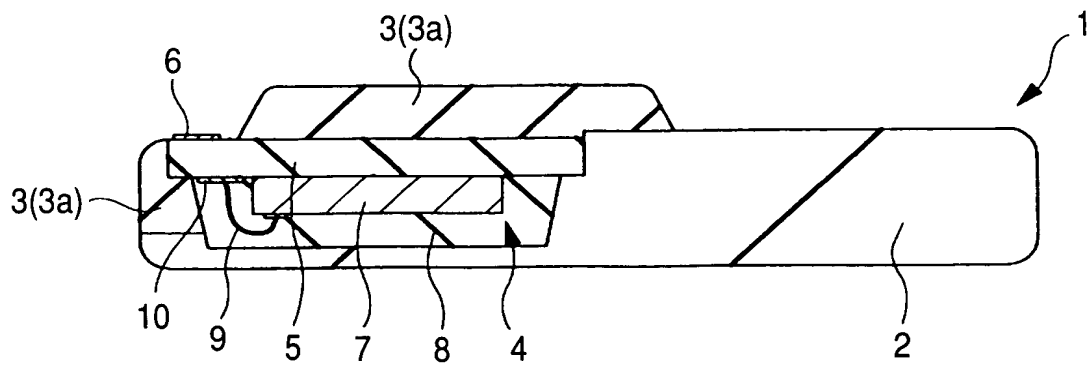


FIG. 22

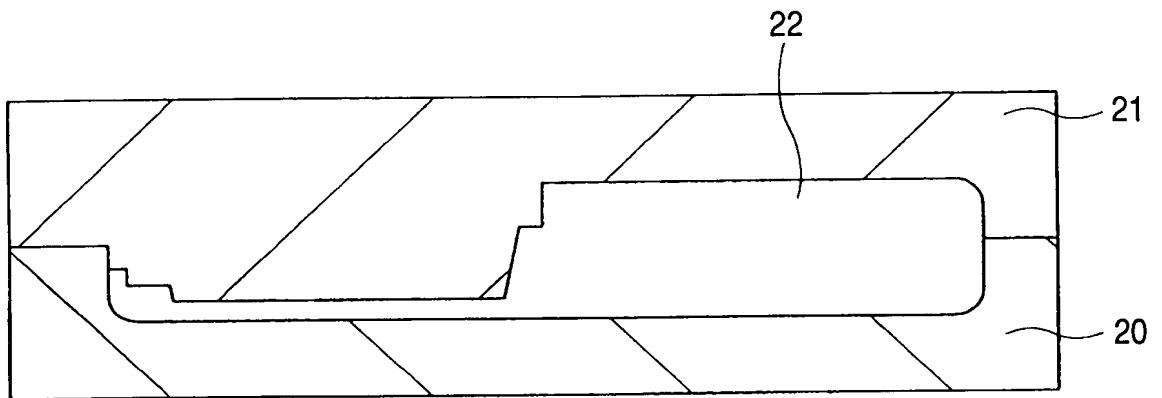


FIG. 23

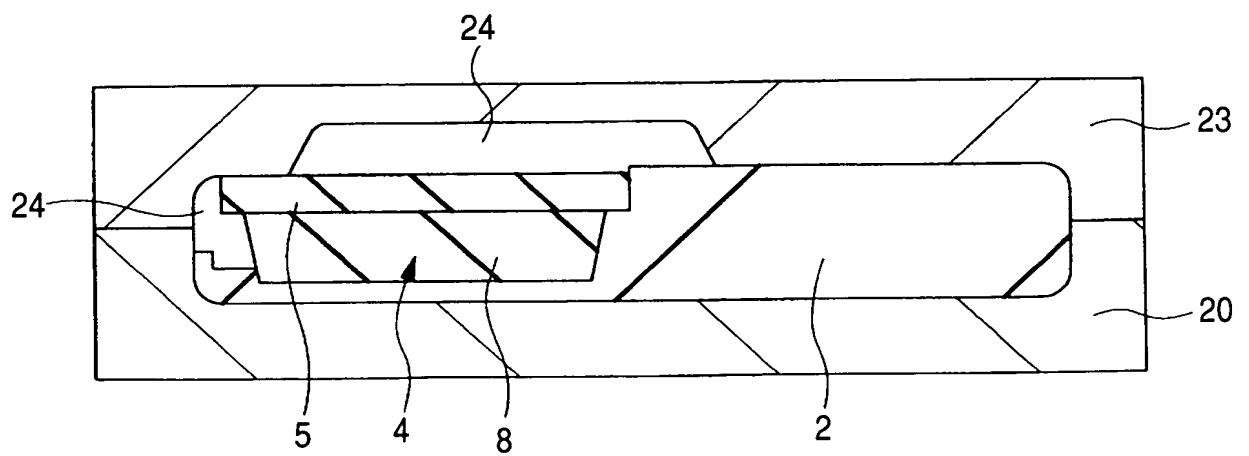


FIG. 24

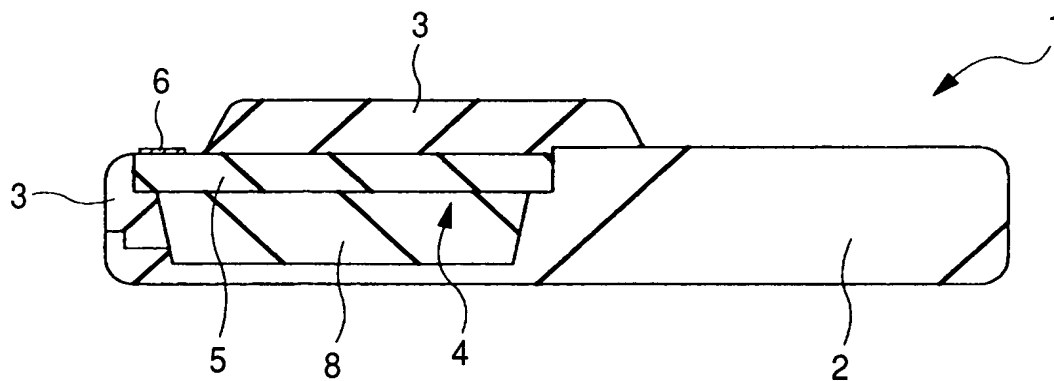


FIG. 25

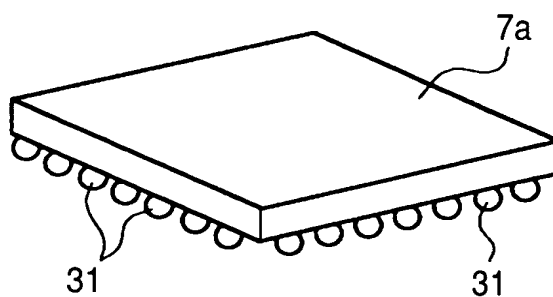


FIG. 26

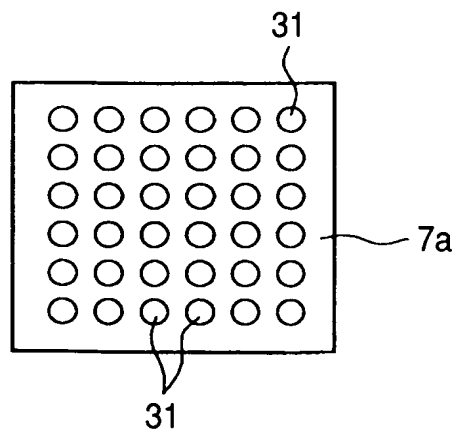


FIG. 27

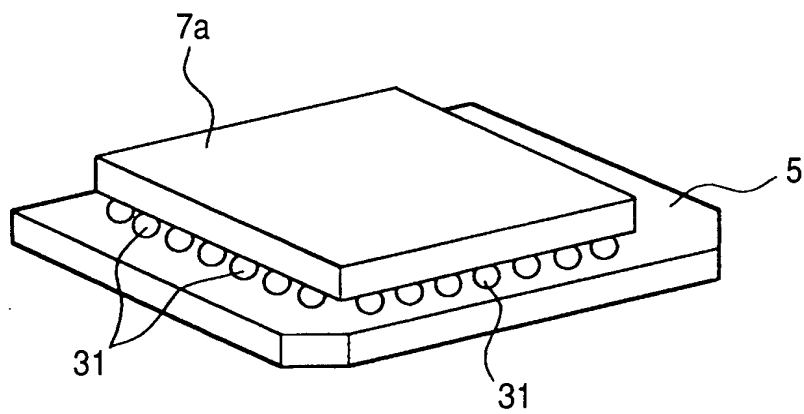


FIG. 28

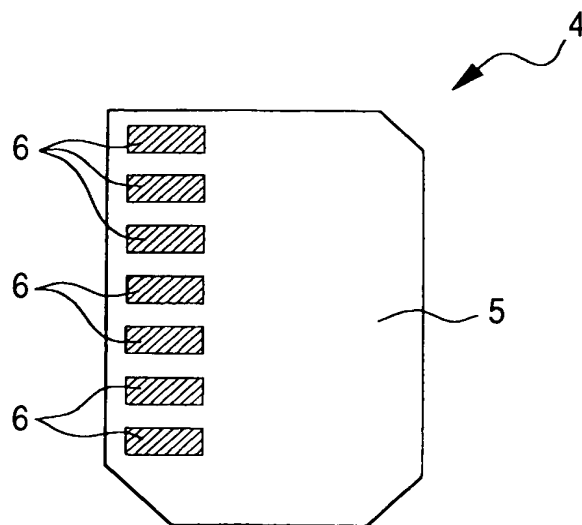


FIG. 29

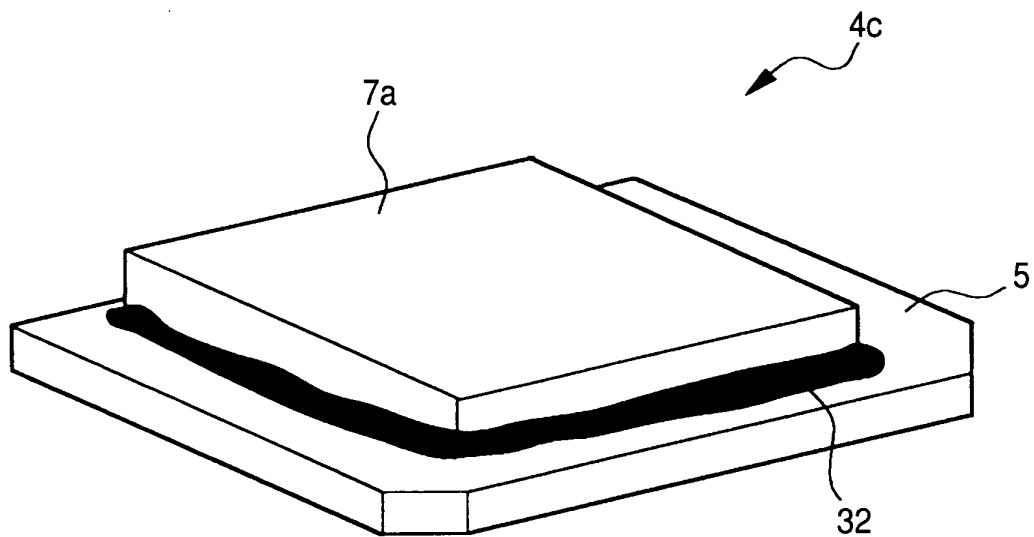


FIG. 30

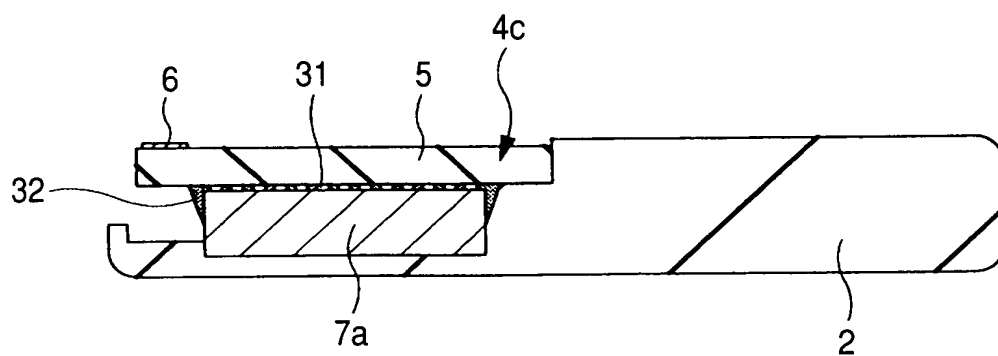


FIG. 31

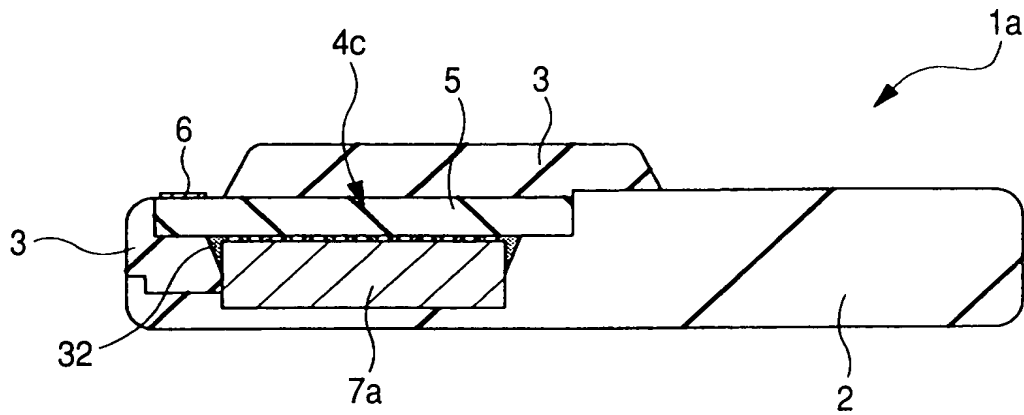


FIG. 32

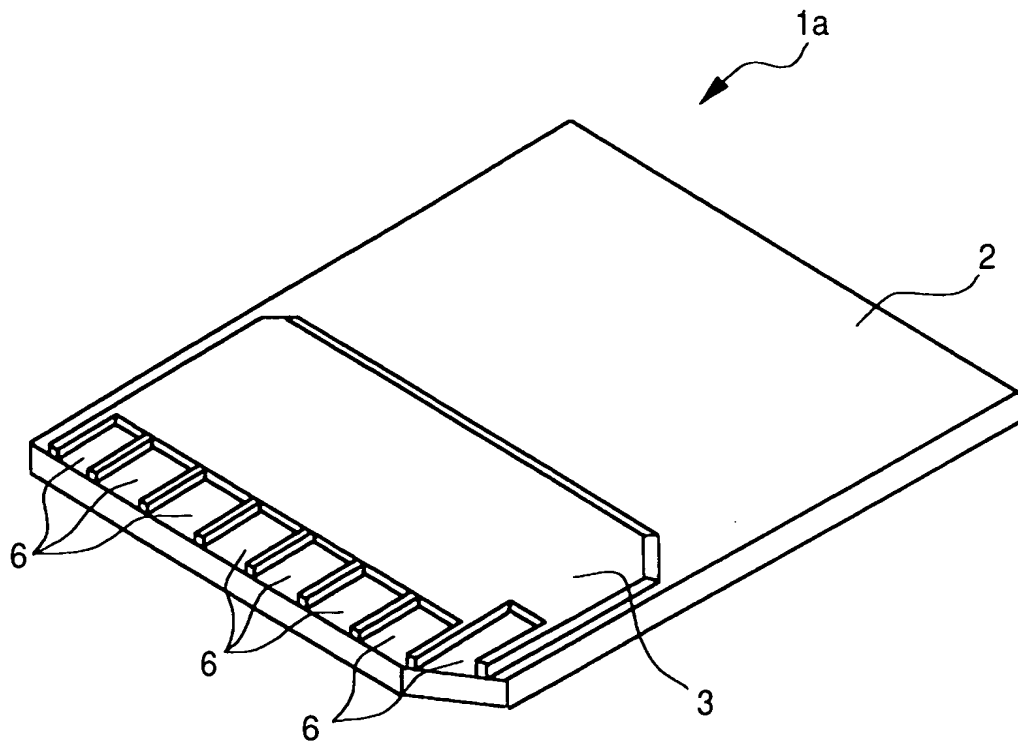


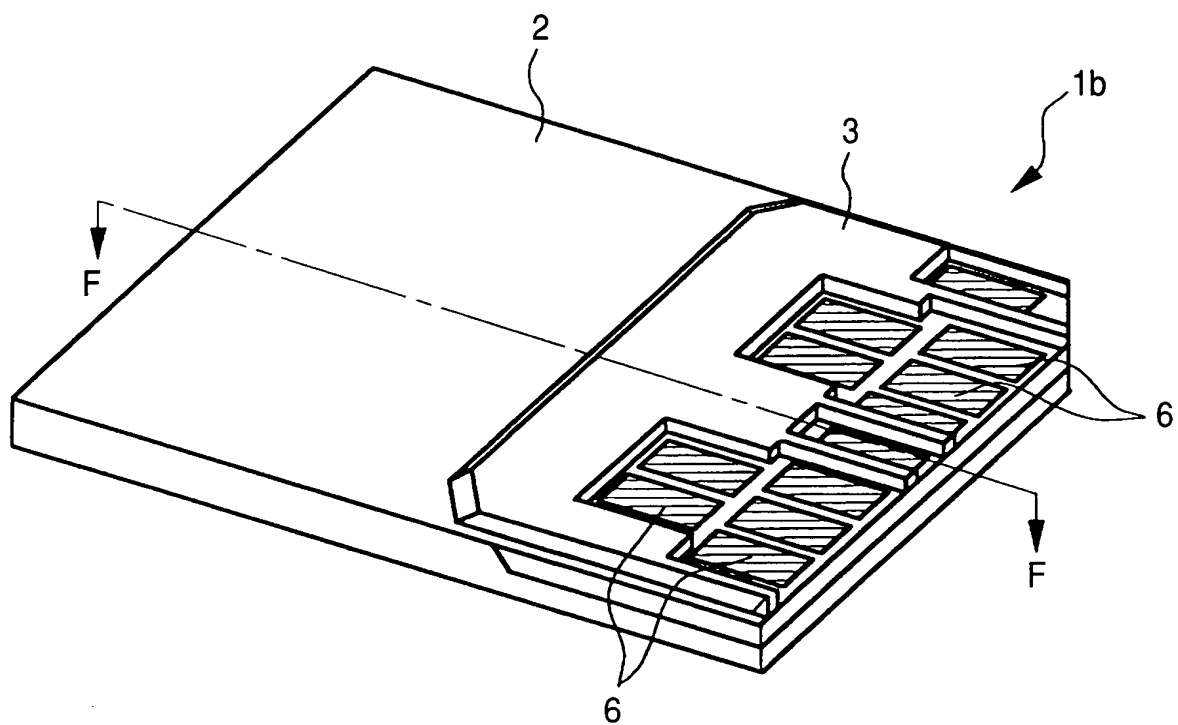
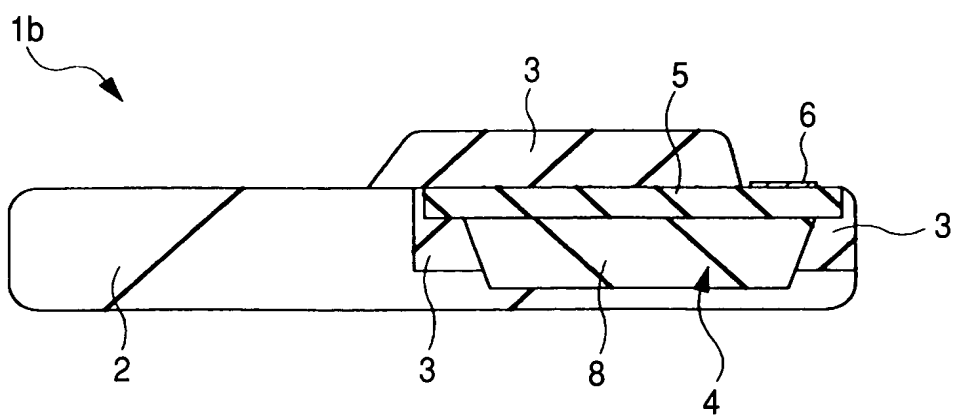
FIG. 33**FIG. 34**

FIG. 35

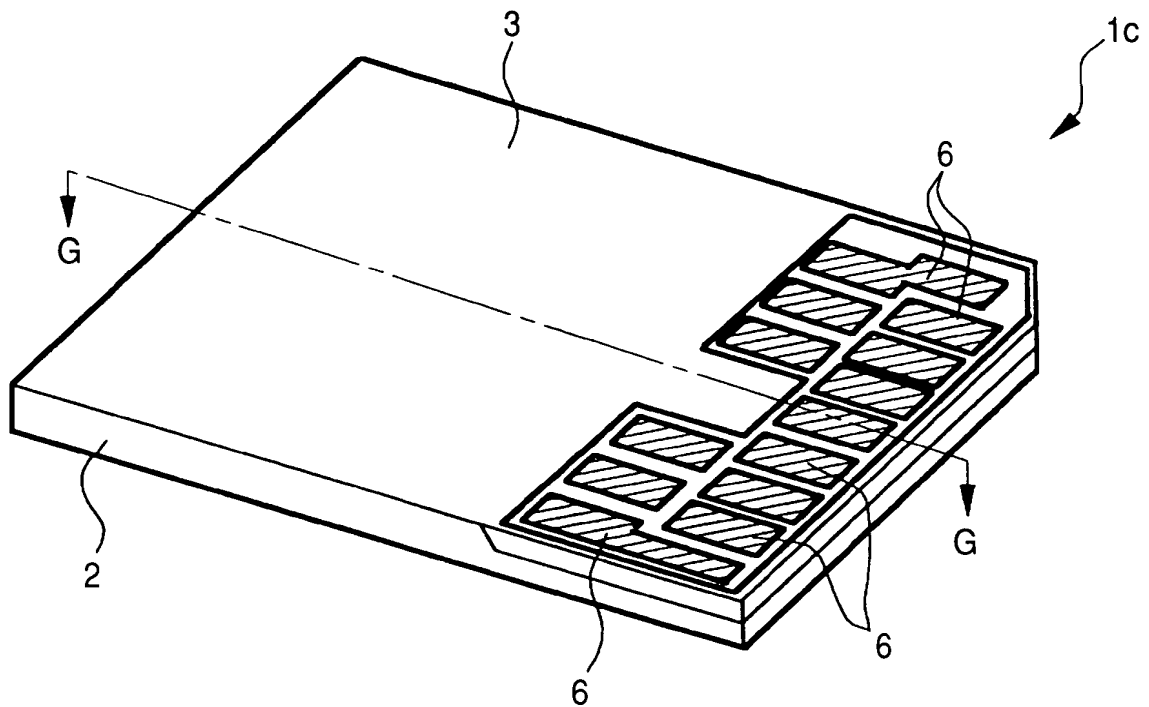


FIG. 36

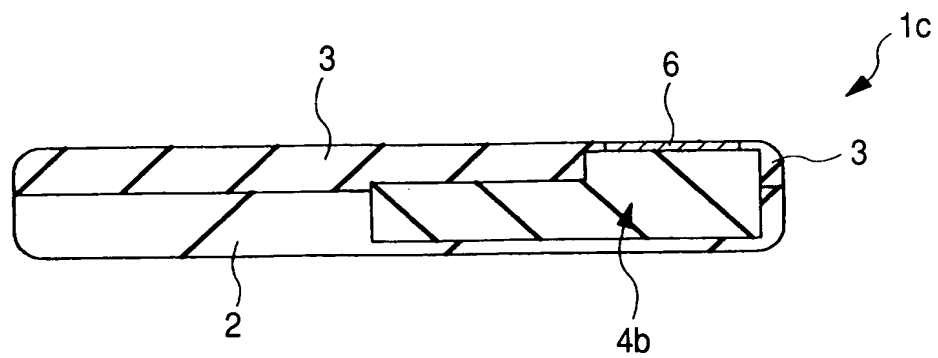


FIG. 37

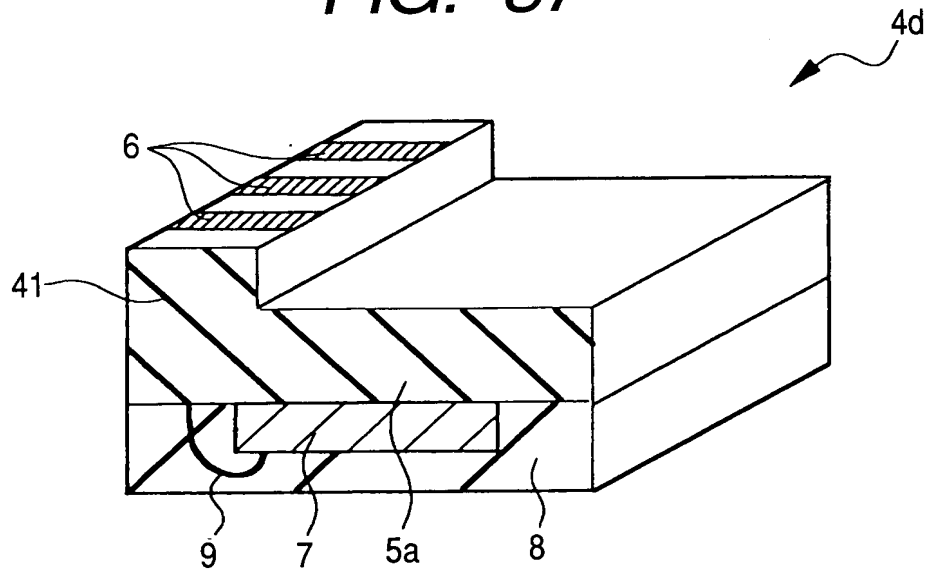


FIG. 38

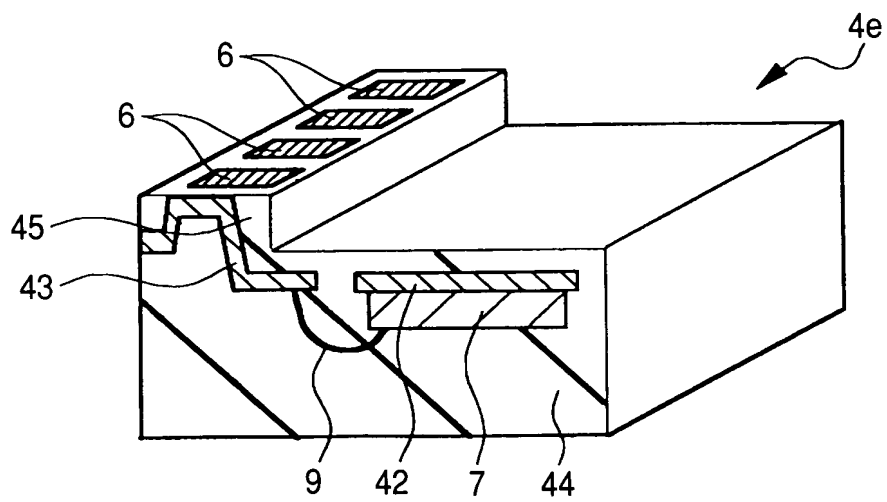


FIG. 39

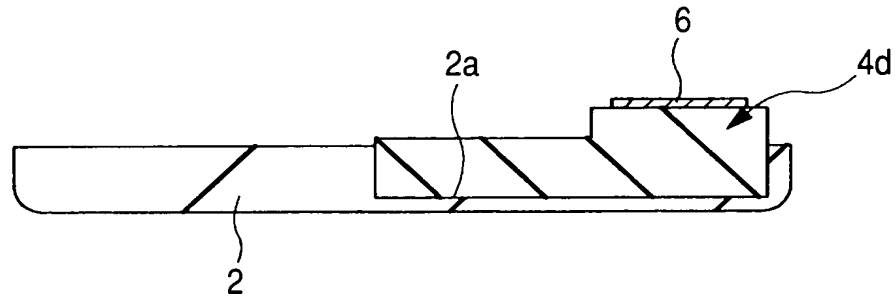


FIG. 40

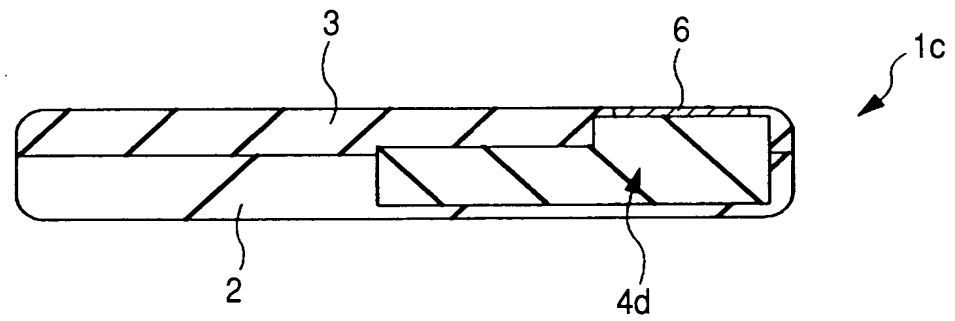


FIG. 41

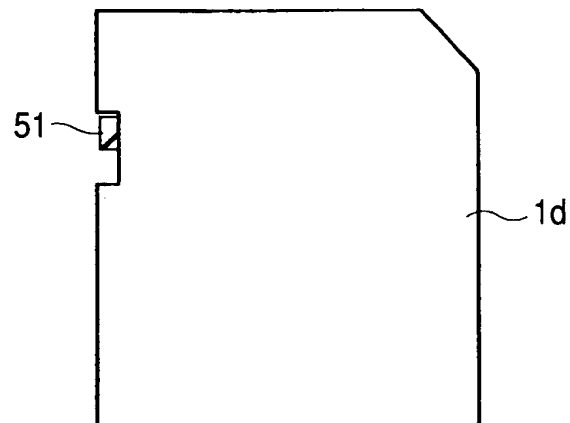


FIG. 42

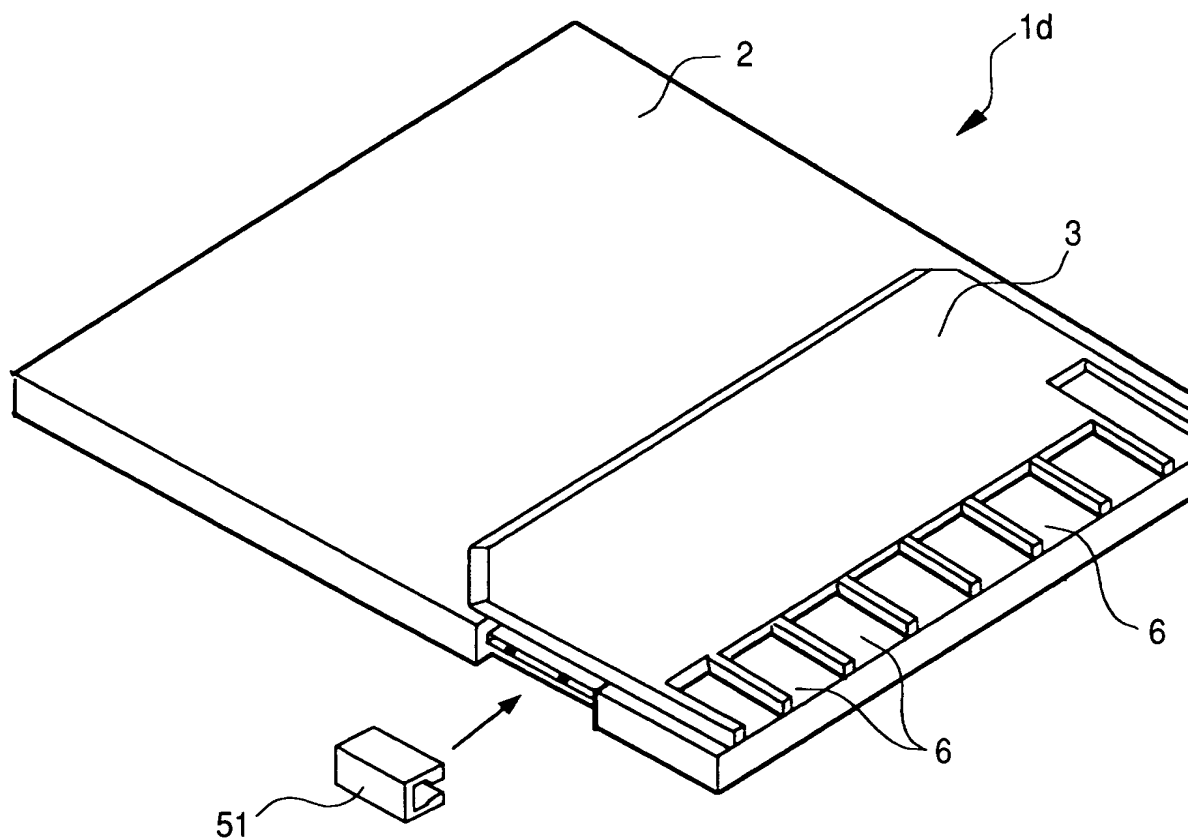


FIG. 43

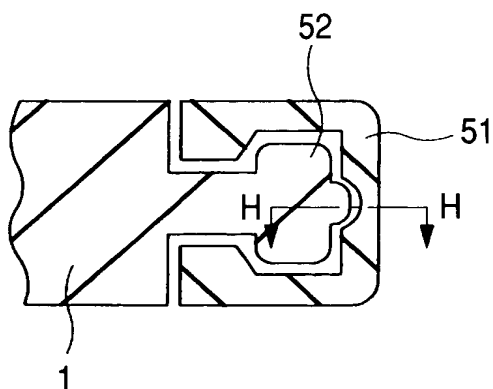


FIG. 44

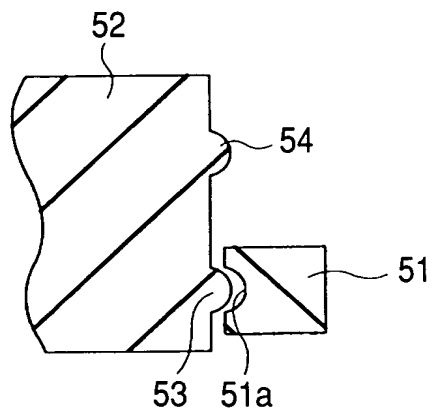


FIG. 45

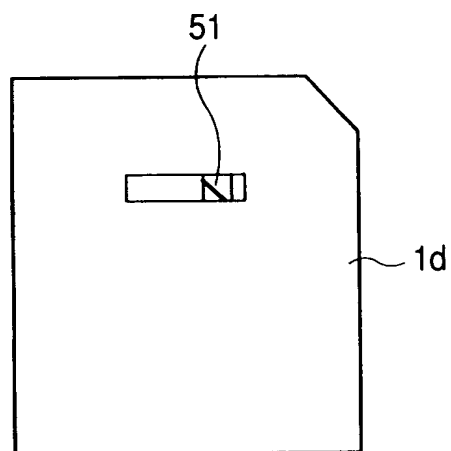


FIG. 46

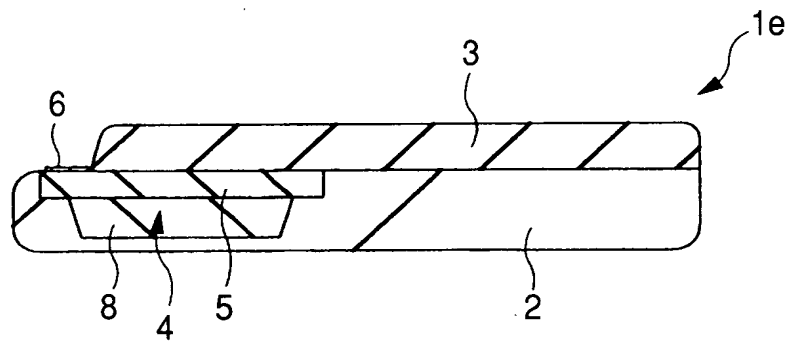


FIG. 47

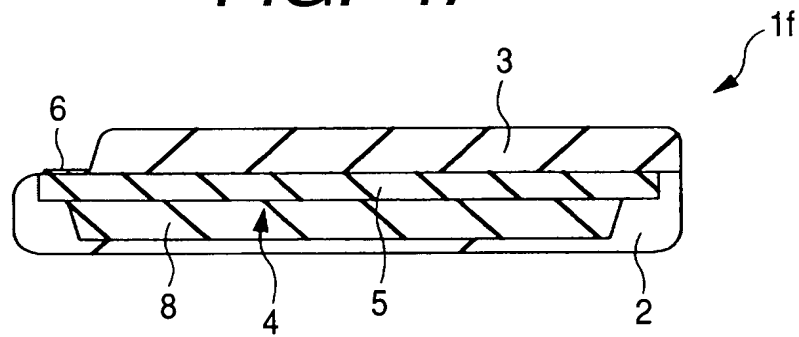


FIG. 48

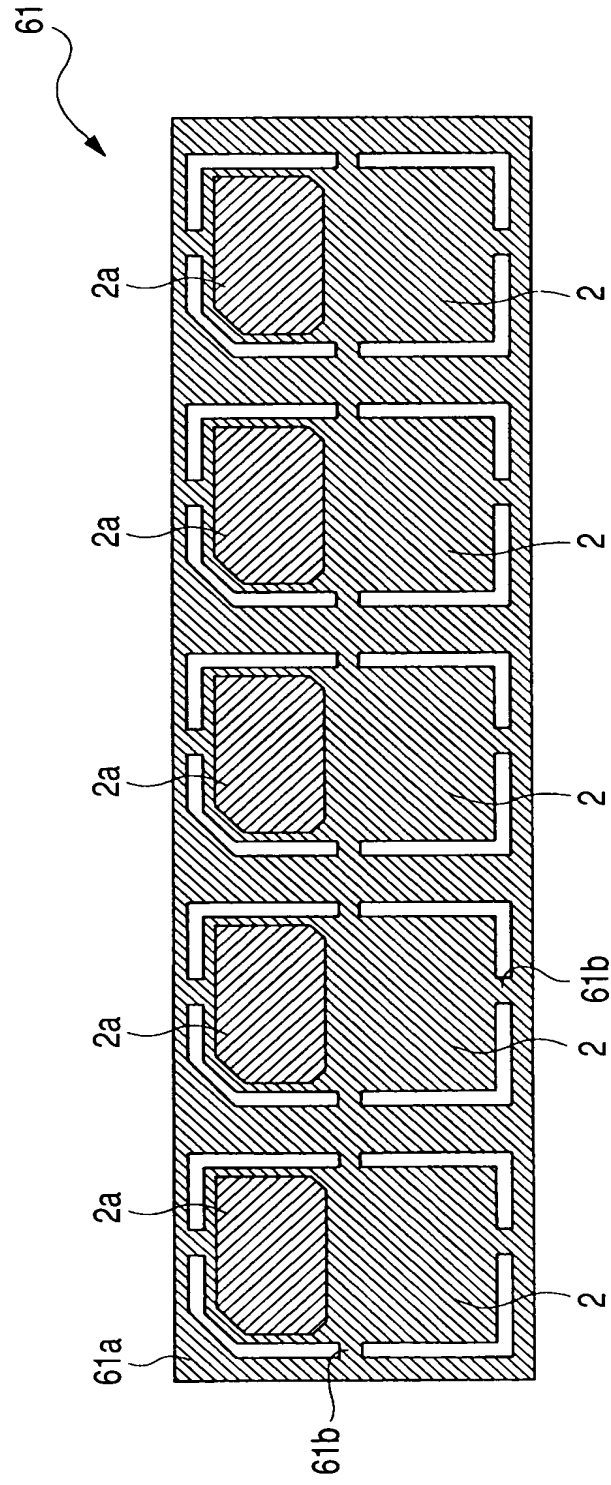


FIG. 49

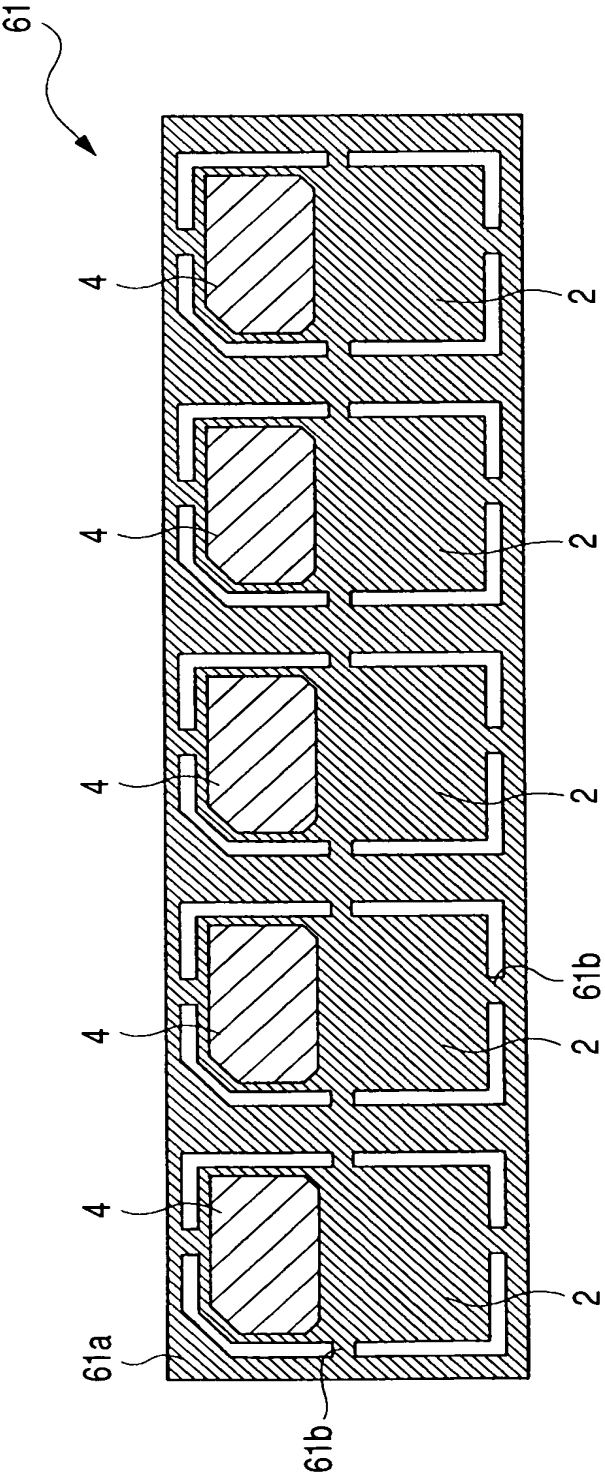


FIG. 50

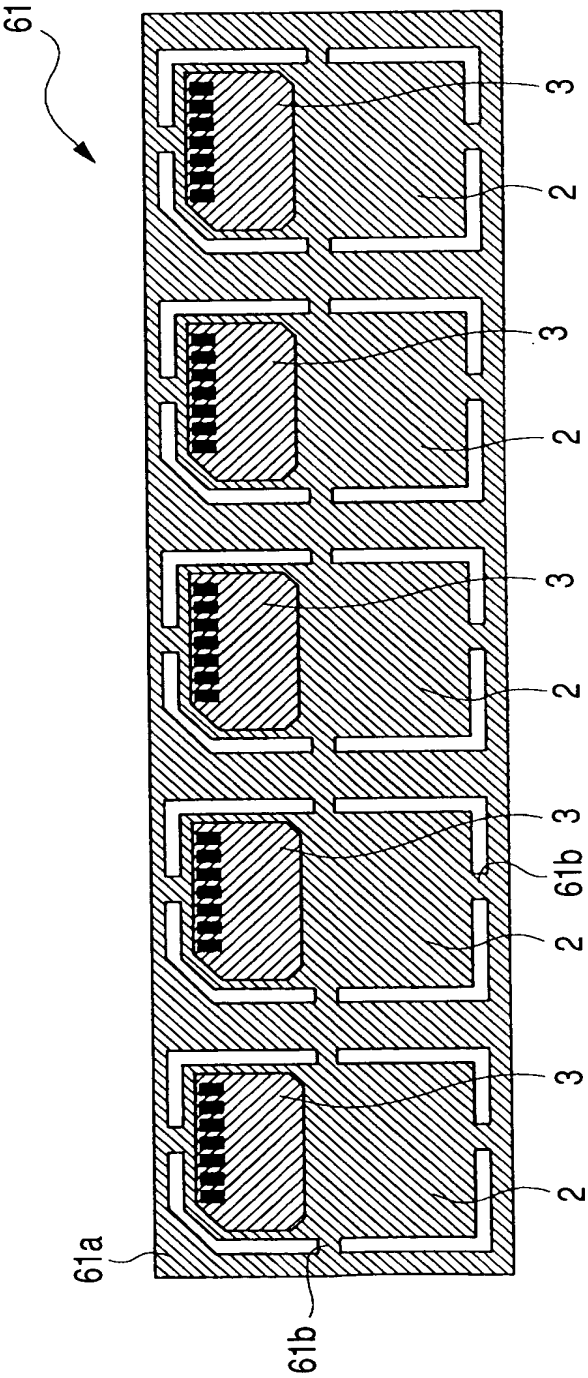


FIG. 51

